



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-02-25
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ACS102-6T1-TR	7T07*A2F102S	A	SHENZHEN B/E	2016-02-25
	Amount	UoM	Unit type	ST ECOPACK Grade
	80.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiPdAuAg	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.9, 6, 1.75	8	GULL WING	
Comment	SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7T07*A2F1025					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.483	mg	supplier	die	Silicon (Si)	7440-21-3		1.419	mg	956844	17738
				supplier	metallization	Aluminium (Al)	7429-90-5		0.012	mg	8092	150
				supplier	Passivation	Silicon Oxide	7631-86-9		0.008	mg	5394	100
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.008	mg	5394	100
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	674	13
				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	2023	38
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.012	mg	8092	150
				supplier	polymer die coating	Probimide	proprietary		0.020	mg	13486	250
Leadframe	Copper & its alloys	32.000	mg	supplier	alloy	Copper (Cu)	7440-50-8		31.911	mg	997219	398888
				supplier	alloy	Iron (Fe)	7439-89-6		0.015	mg	469	188
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.027	mg	844	338
				supplier	metallization	Nickel (Ni)	7440-02-0		0.044	mg	1375	550
				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	31	13
				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	31	13
				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	31	13
Die attach	Other Organic Materials	0.686	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.625	mg	911079	7813
				supplier	glue or tape	acrylate	Proprietary		0.034	mg	49563	425
				supplier	glue or tape	Methacrylate	Proprietary		0.027	mg	39359	338
Bonding wires	Other inorganic materials	0.073	mg	supplier	wire	Copper (Cu)	7440-50-8		0.073	mg	1000000	913
Encapsulation	Other Organic Materials	45.758	mg	supplier	mold compound	Silica, vitreous	60676-86-0		39.626	mg	865991	495325
				supplier	mold compound	Epoxy Resin	25068-38-6		3.432	mg	75003	42900
				supplier	mold compound	Phenol Resin	29690-82-2		2.288	mg	50002	28600
				supplier	mold compound	Carbon black	1333-86-4		0.229	mg	5005	2863
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.183	mg	3999	2288